



Ultra Low Profile 0805 Balun 50Ω to 100Ω Balanced



Description:

The BD2425J50100AHF is a low profile sub-miniature balanced to unbalanced transformer designed for differential inputs and output locations on next generation wireless chipsets in an easy to use surface mount package covering 802.11b+g+n. The BD2425J50100AHF is ideal for high volume manufacturing and is higher performance than traditional ceramic and lumped element baluns. The BD2425J50100AHF has an unbalanced port impedance of 50□ and a 100□ balanced port impedance. This transformation enables single ended signals to be applied to differential ports on modern semiconductors. The output ports have equal amplitude (-3dB) with 180 degree phase differential. The BD2425J50100AHF is available on tape and reel for pick and place high volume manufacturing.

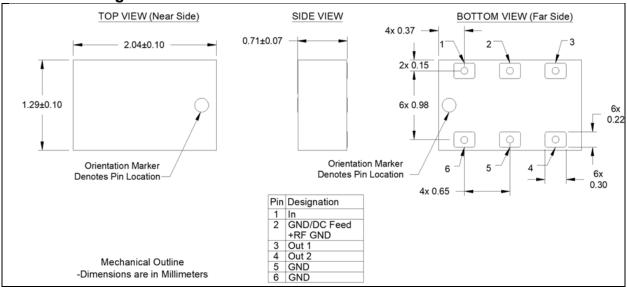
Detailed Electrical Specifications:

Specifications subject to change without notice.

		ROOM (25°C)			
<u>Features:</u>	Parameter	Min.	Тур.	Max	Unit
• 2400 – 2500 MHz	Frequency	2400		2500	MHz
0.7mm Height Profile50 Ohm to 2 x 50 Ohm	Unbalanced Port Impedance		50		Ω
• 802.11 b+g +n Compliant	Balanced Port Impedance		100		Ω
Low Insertion Loss	Return Loss	14	22		dB
Input to Output DC	Insertion Loss*		0.55	0.75	dB
Isolation	Amplitude Balance		0.3	0.5	dB
Surface MountableTape & Reel	Phase Balance		2	5	Degrees
Non-conductive Surface	CMRR		33		dB
RoHS Compliant	Power Handling @85C			2	Watts
Halogen Free	Power Handling @105C			1.2	Watts
	Operating Temperature	-55		+105	°C

^{*} Insertion Loss stated at room temperature (Insertion Loss is approximately 0.1 dB higher at +85 °C).

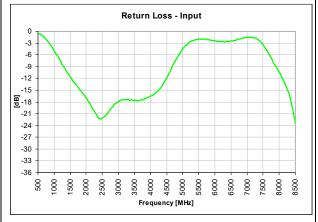
Outline Drawing



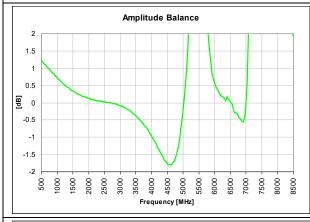


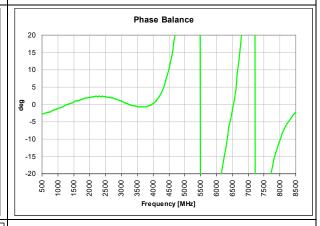


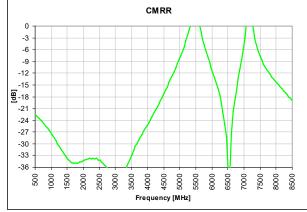
Typical Broadband Performance: 500 MHz. to 8500 MHz.







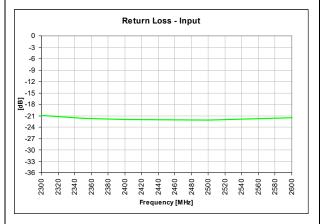


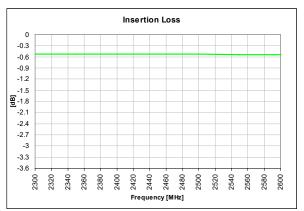


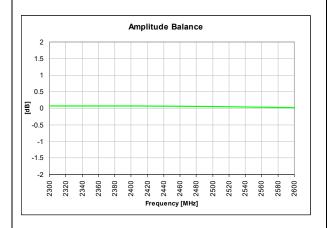


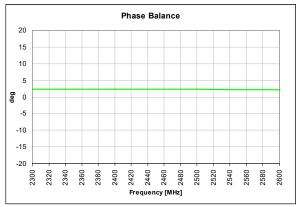


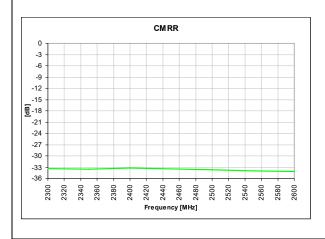
Typical Performance: 2300 MHz. to 2600 MHz.













Mounting Configuration:

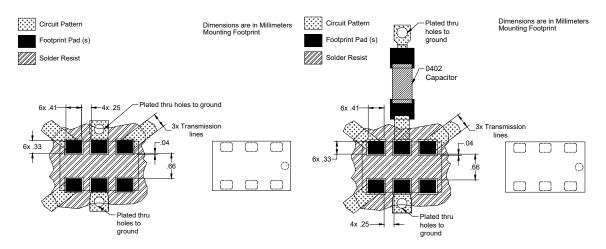
In order for Xinger surface mount components to work optimally, the proper impedance transmission lines must be used to connect to the RF ports. If this condition is not satisfied, insertion loss, Isolation and VSWR may not meet published specifications.

All of the Xinger components are constructed from organic PTFE based composites which possess excellent electrical and mechanical stability. Xinger components are compliant to a variety of ROHS and Green standards and ready for Pb-free soldering processes. Pads are Gold plated with a Nickel barrier.

An example of the PCB footprint used in the testing of these parts is shown below. An example of a DC-biased footprint is also shown below. In specific designs, the transmission line widths need to be adjusted to the unique dielectric coefficients and thicknesses as well as varying pick and place equipment tolerances.

No Bias Footprint

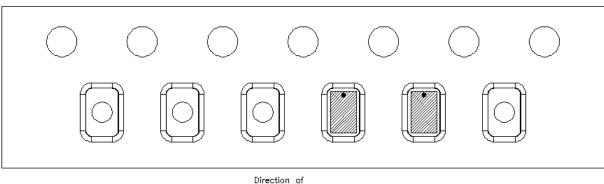
DC Bias Footprint

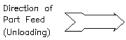




Packaging and Ordering Information

Parts are available in reel and are packaged per EIA 481-D. Parts are oriented in tape and reel as shown below. Minimum order quantities are 4000 per reel.





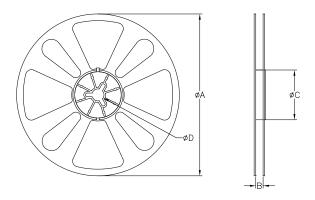


TABLE 1						
QUANTITY/REEL	REEL DIMENSIONS mm					
	ØΑ	177.80				
4000	В	8.00				
,,,,,	ФC	50.80				
	øD	13.00				

Contact us:

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